



WOOD H910 SILENTSTIK

ACOUSTIC ADHESIVE FOR PARQUET FLOORS

KEY BENEFITS

- **High acoustic performance: impact noise and airborne noise**
- **2 in 1: bonding and acoustics properties in one product**
- **Suitable for underfloor heating**



APPLICATIONS

DESCRIPTION

WOOD H910 SILENTSTIK is an adhesive system with integrated soundproofing

DESTINATION

WOOD H910 ELASTIC-P is suitable for the laying of the following parquet floors :

- Factory varnished solid parquet or raw parquet up to 150 mm wide, all thicknesses.
- Factory varnished or raw parquet, all thicknesses and widths.
- all types of wood (except beech).
- All wood species including horn-beech, beech, birch and bamboo

Associated floor coverings :

- Porous or non-porous cement-based subfloors
- Anhydrite screed
- Old ceramic tiles
- Wood subfloors
- Metal subfloors

PRODUCT CHARACTERISTICS

Colour	brown-beige
Composition	Acoustic adhesive
Storage / Shelf life*	18 months
Application temperature	+10°C to +30°C
Open time**	40 min
Blocking time**	2 hours
Walk on time**	24 hours
Curing time* *	24 to 48 hours
Coverage	1,6-2 kg/m ²

*from date of manufacture in original, unopened packaging, clear of the ground, in cool, dry conditions within the temperature range +5°C to +25°C and out of direct sunlight. Protect from frost, damp, condensation and dew.

**these times are determined at + 23° C and 50 % relative humidity on normally absorbent substrates

DIRECTION FOR USE

PREPARATION

Ensure the subfloor is in accordance with building standards. Subfloors must be clean, sound, dry (<75%RH), and free from contaminants that may impair adhesion e.g. dust, grease, paint, plaster, polish, water softenable adhesive etc.

Ensure the timber is acclimatised in accordance to the manufacturer's instructions in the environment in which it is to be laid. Always allow an expansion gap around any perimeters or columns to allow for natural movement of the wood when bonded. Follow the manufacturer's instructions with regards to washer gaps on wide expanses of floor and for use of expansion gaps at doorways or where thresholds are present.

For subfloors that are not sufficiently smooth or require height build up to receive the particular floor covering being bonded, an application of a suitable Bostik smoothing compound and primer system is recommended. Please consult Technical Services for advice on specific products and subfloors.

Priming is not required.

Before applying any adhesive, ensure the substrate is dry and dust free.

Underfloor heating systems:

Underfloor heating systems must be switched off for 48 hours before installation. Wait 7 days after installation before gradually turning up underfloor heating.

APPLICATION

Ensure a good overall contact is achieved between wood and substrate. Spread the adhesive with a spatula, forming continuous and regular glue furrows; The grooves are made perpendicular to the parquet strips or slightly at an angle (angle of 20 to 30° max.).

Place the wood into the adhesive while it is still wet. Only apply enough to work within in 40 minutes.

Press firmly to ensure good overall contact. Use heavy objects to hold the wood firmly in place during the curing time.

Distorted floorboards need to be weighted until the adhesive is fully cured.

Using wedges, allow a gap of 8mm between the parquet and walls. Remove the wedges immediately after installation.

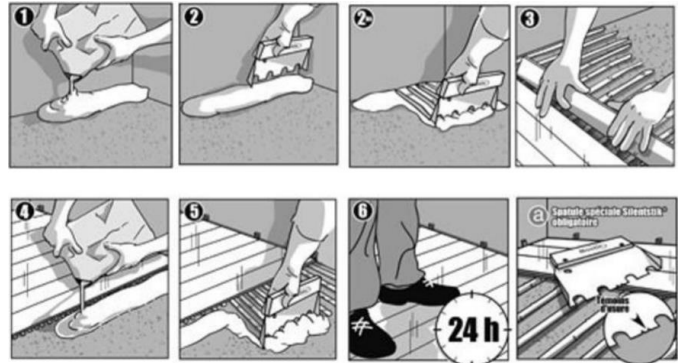
DRYING TIMES

The bonded wood should take foot traffic after 24 hours.

Leave bonded wood 48 hours before sanding and varnishing.

IMPLEMENTATION STEPS

The use of the special WOOD H910 SILENTSTIK® trowel is mandatory. Use the reinforcing ribs to shape the glue grooves



Cut a corner of the aluminised bag and pour the WOOD H910 SILENTSTIK® glue along the starting line of the parquet installation work.

CLEANING

Clean tools and equipment with white spirit immediately after use.

Do not allow to cure, remove excess adhesive immediately by scraping off, then cleaning with a cloth dampened with white spirit (always test for colourfastness on small trial area first). Cured adhesive can only be removed mechanically.

Code	UC	PALLET.	PCB	GENCOD
30618143	15 kg	24	1	3549210030928



SAFETY

For more details, consult the safety data sheet on <https://bostikds.thewerco.com/default.aspx>

The information given and recommendations made herein are based on Bostik's research only and are not guaranteed to be accurate. The performance of the product, its shelf life, and application characteristics will depend on many variables, including the kind of materials to which the product will be applied, the environment in which the product is stored or applied, and the equipment used for application. Any change in any of these variables can affect the product's performance. It is the buyer's obligation, prior to using the product, to test the suitability of the product for an intended use under the conditions that will exist at the time of the intended use. Bostik does not warrant the product's suitability for any particular application. The product is sold pursuant to Bostik's Terms and Conditions of Sale that accompanies the product at the time of sale. Nothing contained herein shall be construed to imply the nonexistence of any relevant patents or to constitute permission, inducement, or recommendation to practice any invention covered by any patent, without authority from the owner of the pat

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